

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward Continuous Current (Note 5)	I _{FM}	200	mA
Repetitive Peak Forward Current	I _{FRM}	500	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0μs	4
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	250	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R _{θJA}	500	°C/W
Thermal Resistance Junction to Solder Point (Note 6)	R _{θJSP}	260	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	100	—	V	I _R = 2.5μA
Forward Voltage	V _F	—	0.715	V	I _F = 1.0mA
		—	0.855		I _F = 10mA
		—	1.0		I _F = 50mA
		—	1.25		I _F = 150mA
Reverse Current (Note 7)	I _R	—	0.5	μA	V _R = 80V
		—	50		V _R = 80V, T _J = +150°C
		—	30	nA	V _R = 25V, T _J = +150°C
		—	30		V _R = 25V
Total Capacitance	C _T	—	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{RR}	—	4.0	ns	I _F = I _R = 10mA, I _{RR} = 0.1 × I _R , R _L = 100Ω
Forward Recovery Voltage	V _{FR}	—	1.75	V	I _F = 10 mA; t _r = 20ns

- Notes:
- Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Soldering points at pins AC₁, AC₂ and C₁, C₂.
 - Short duration pulse test used to minimize self-heating effect.

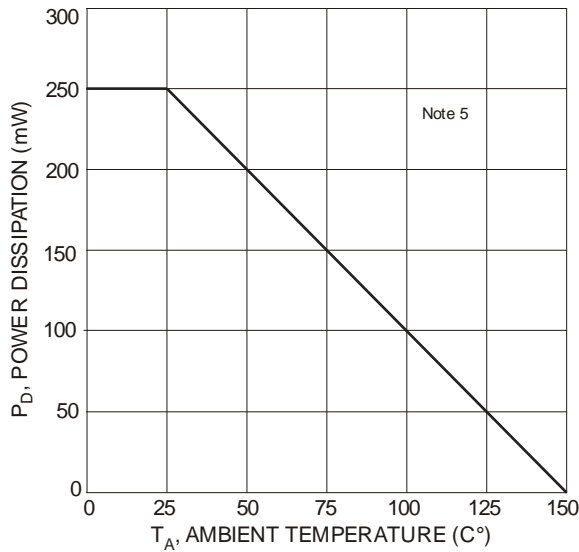


Fig. 1 Power Derating Curve, Total Package

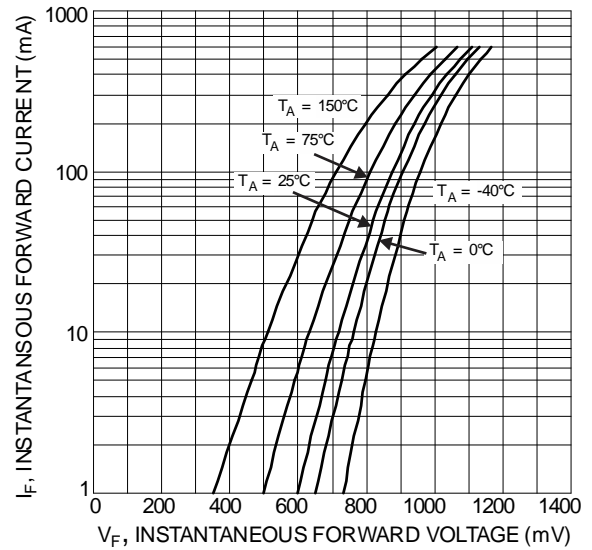


Fig. 2 Typical Forward Characteristics

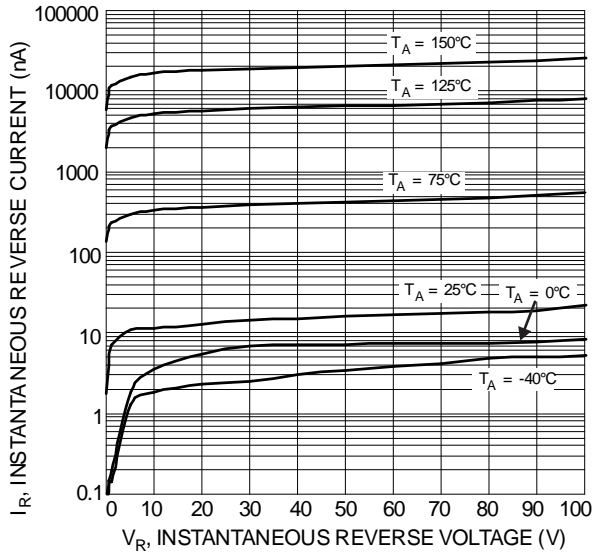


Fig. 3 Typical Reverse Characteristics, Per Element

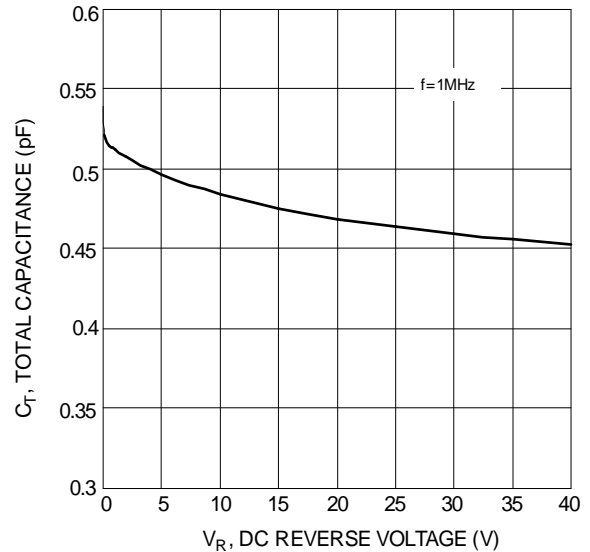
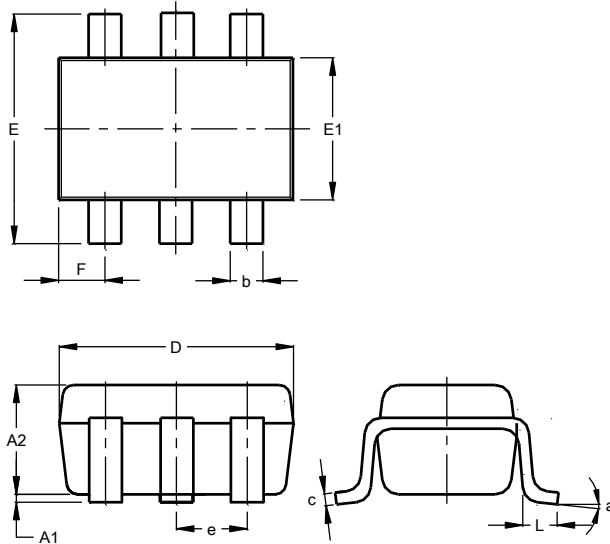


Fig. 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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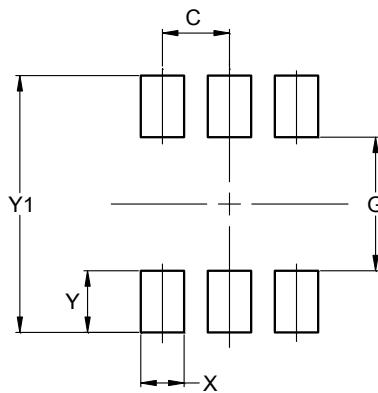


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Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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